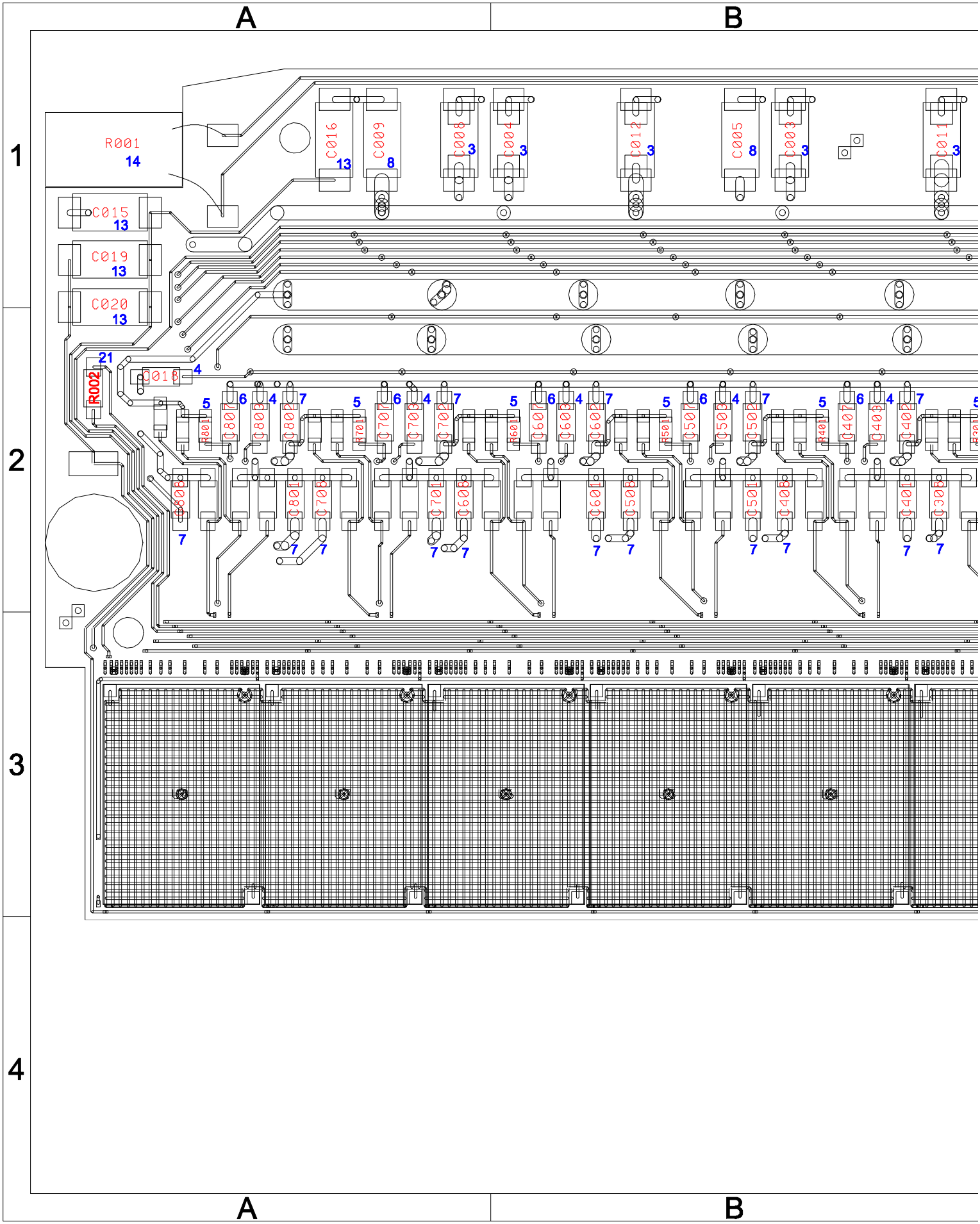
A
B
1
2
3
4
R001
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C016
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C004
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C003
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C011
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C015
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C019
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C020
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21
R002
C018
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C801
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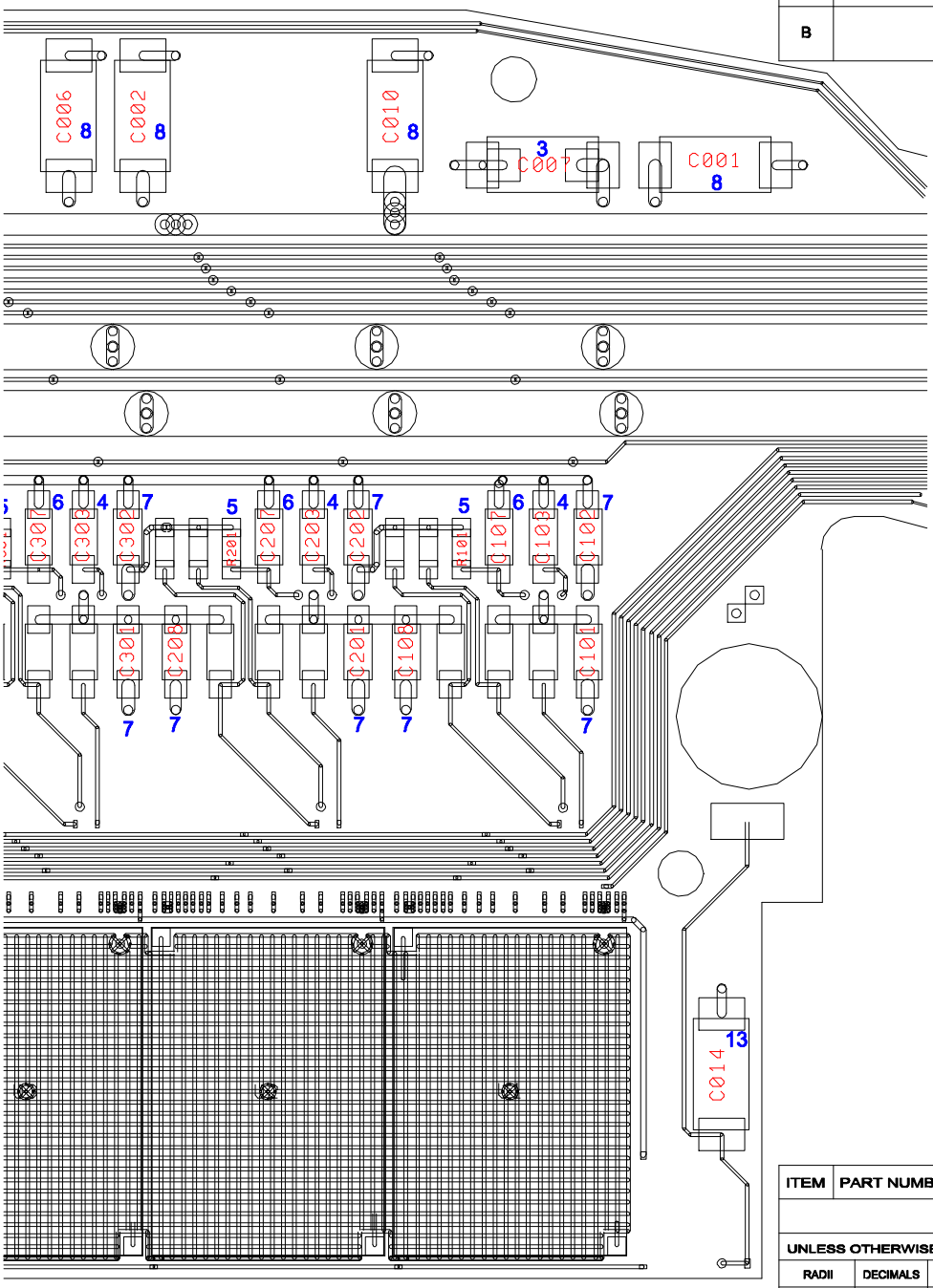
REV.	DESCRIPTION	DRAWN	DATE
		APPD.	DATE
B	ADDED R002.	M. MATULIK	08/26/99



ITEM	PART NUMBER	DESCRIPTION OR SIZE	QTY

PARTS LIST

UNLESS OTHERWISE SPEC.		ORIGINATOR	M. Matulik	03/25/99
RADII	DECIMALS	DRAWN BY	M. Matulik	03/25/99
0.030	0.005	CHECKED BY		
DIMENSIONS IN INCHES.		APPROVED BY		
		USED ON -		
		MATERIAL -		

FERMI NATIONAL ACCELERATOR LABORATORY
UNITED STATES DEPARTMENT OF ENERGY

HIGH DENSITY INTERCONNECT
8 CHIP F-DISK HDI
BONDING DIAGRAM

SCALE	FILMED	DRAWING NUMBER	Sheet 1 of 1	REV.
		3823.112-MB-330253		B